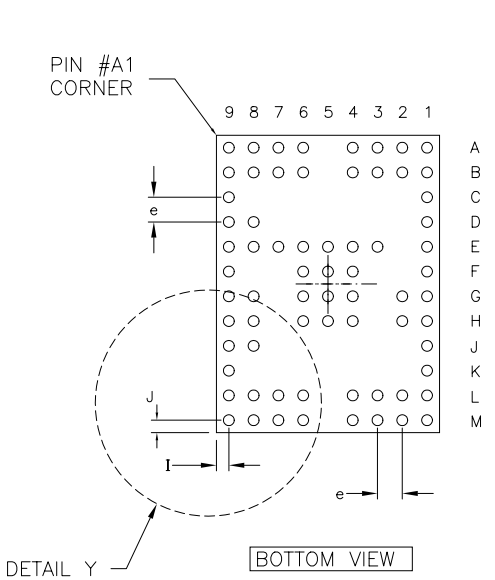
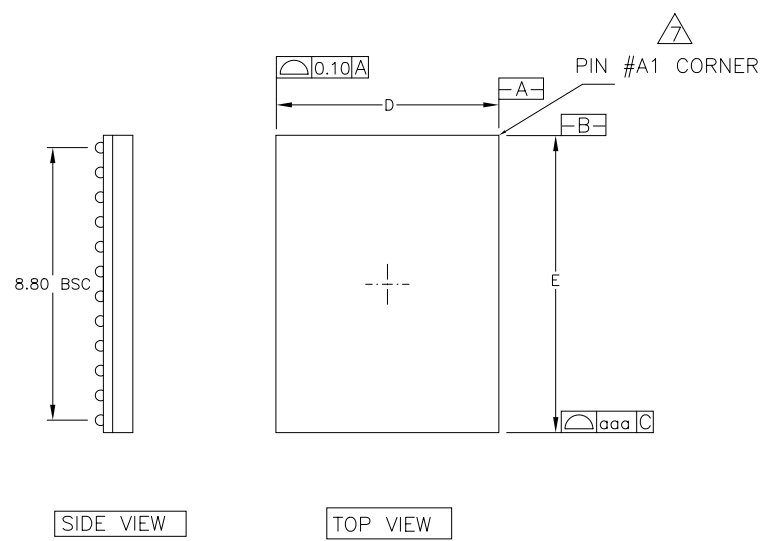
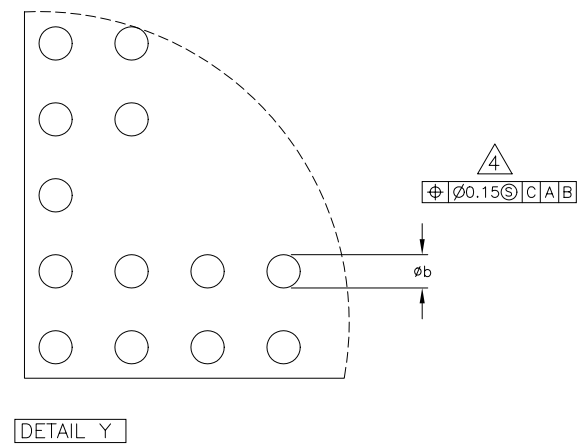
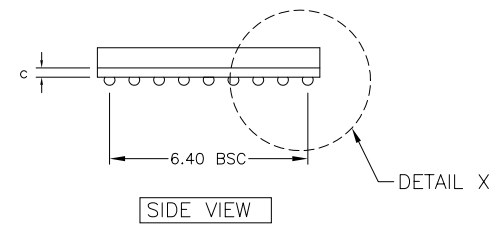


REV.	DESCRIPTION	DATE	ENG	APPROVAL
-	GENERATION	08/29/01	MS PARK	

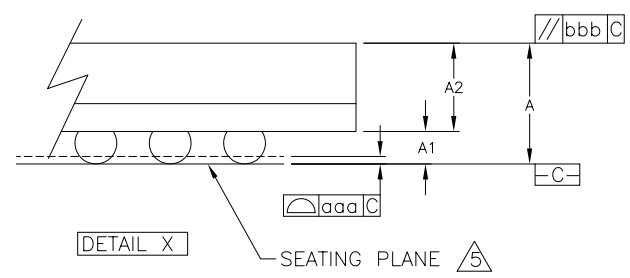


NOTE:

- ALL DIMENSIONS ARE IN MILLIMETERS.
- "e" REPRESENTS THE BASIC SOLDER BALL GRID PITCH.
- "M" REPRESENTS THE MAXIMUM SOLDER BALL MATRIX SIZE.
- DIMENSIONS "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER PARALLEL TO PRIMARY DATUM \boxed{C} .
- PRIMARY DATUM \boxed{C} AND SEATING PLANE ARE DESIGNED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
- DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994
- A1 CORNER MUST BE IDENTIFIED BY INK OR LASER MARK.



SYMBOL	MIN.	NOM.	MAX.
A	1.02	1.12	1.17
A1	0.20	0.25	0.30
A2	0.82	0.87	0.92
D	7.10	7.20	7.30
E	9.50	9.60	9.70
I	0.40 REF.		
J	0.40 REF.		
M	9X12 <DEPOPULATED>		
aaa			0.10
bbb			0.10
b	0.30	0.35	0.40
c	0.24	0.27	0.30
e	0.80 TYP.		



LIST OF MATERIAL AND APPLICABLE DOCUMENTS							
SCALE:	N/S	DATE:	08/29/01	DRAWN:	MS PARK	TITLE: FBGA 7.2X9.6mm 69 BALL 0.80MM BALL PITCH PACKAGE OUTLINE FOR U-PEN.	
DIMENSIONAL UNIT:	MM	UNTOLERANCED DIMENSIONS		ENGINEER:	MS PARK		
PROJECTION		FRAC:	.X ± 0.10	CHECKED:	YB KIM		
UNLESS SPECIFIED		.XX ± 0.05 .XXX ± 0.03 ANGLE ± 1		APPROVED:	-		
		CAD NAME:	EEV-OLB72961	DRAWING NUMBER:	EEV-OLB72961	REV.	SHEET:
						-	1 OF 1